UPKTECH UPKTECH Technology Co., Ltd

Room 207, Building 2, No. 5, Yangchong Industrial Zone, Songgang Street, Bao'an District, Shenzhen, Guangdong Province, China

TEL: +8613825258612 Postcode:518105

GKG GT++ Fully Automatic Solder Paste Printer Used / New

Introduction:

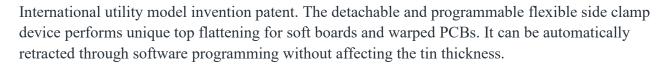
1. Drip cleaning system

Drip cleaning structure effectively prevents the solvent tube from blocking the hole and causing the local solvent-free and unclean wiping.

2. Brand-new scraper structure design

The new scraper structure of the slide rail and cylinder improves the operation stability and extends the service life.

3. Guide rail positioning system



4. CCD digital camera system

The brand-new optical path system-uniform annular light and high-brightness coaxial light, with infinitely adjustable brightness function, makes all types of Mark points can be well identified (including uneven Mark points) to adapt to tin-plated, copper-plated, gold-plated, tin-sprayed, FPC and other types of PCBs of different colors.

5. High-precision PCB thickness adjustment lifting platform

Compact and reliable structure, stable lifting and lowering, PIN height software automatic adjustment, can accurately adjust the position height of PCB boards of different thicknesses.

6. New multi-functional interface

Simple and clear, easy to operate. Real-time temperature remote control function.

Optional functions

1. Bottle-type automatic tinning and solder paste detection function

Mobile automatic solder paste addition to ensure solder paste quality and solder paste amount in steel mesh, thereby ensuring customer printing quality and improving productivity.



UPICTECH UPKTECH Technology Co., Ltd

Room 207, Building 2, No. 5, Yangchong Industrial Zone, Songgang Street, Bao'an District, Shenzhen, Guangdong Province, China

TEL: +8613825258612 Postcode:518105

2. Automatic glue dispensing system

According to different printing process requirements, after printing, the PCB board can be accurately dispensed, tinned, line drawn, filled and other functions; at the same time, the glue dispensing head is also equipped with a heating function, which can heat the glue when the ambient temperature is low to improve the fluidity of the glue.

3. SPI connection

Connected with SPI to form a closed-loop system. When receiving feedback information about poor printing from SPI, the machine will automatically adjust according to the SPI feedback offset. The XY direction offset can be automatically adjusted within 3PCS, and the steel mesh will be cleaned to improve printing quality and production efficiency, forming a complete printing feedback system.

4. Steel mesh detection function

By performing light source compensation above the steel mesh, using CCD to check the mesh of the steel mesh in real time, it can quickly detect and determine whether the steel mesh is blocked after cleaning, and automatically clean it, which is a supplement to the 2D detection of the PCB board.

5. Leading the compatibility of Industry 4.0

By automatically uploading or outputting the machine status and parameters, it provides strong guarantees for the intelligent production of Industry 4.0 for customers. It can achieve seamless docking with the customer's MES system and achieve high traceability of products; intelligently control equipment maintenance, and realize self-allocation of usage rights for engineers at all levels according to on-site management.

6. BTB

Double tracks bring twice the performance: the two devices can be controlled separately, for example running different products on each track; the two devices can be separated again at any time.

Model GT++

Screen frame size $470\times370-737\times737$ mm Substrate size $50\times50-510\times510$ mm

Substrate thickness 0.4-6mm

Substrate weight 5Kg
Substrate edge gap 2.5mm

www.smtbank.com

UPKTECH UPKTECH Technology Co., Ltd

Room 207, Building 2, No. 5, Yangchong Industrial Zone, Songgang Street, Bao'an District, Shenzhen, Guangdong Province, China

TEL: +8613825258612 Postcode:518105

Transmission height 23mm

Transmission height 900±40mm

Transport speed 1500mm/S (MAX) Software control (speed adjustable)

Transmission method One-stage transport guide rail

Substrate support method

Magnetic ejector pin/equal height block/automatic adjustment of lifting

platform

Substrate clamping method

Automatic telescopic upper pressure plate/flexible clamping edge/vacuum

adsorption function

Printing demolding 0-20mm

Printing mode Single or double scraper printing

Scraper type Rubber scraper/steel scraper (angle 45°/55°/60°)

Scraper speed 6-200mm/sec Printing pressure 0.5-10Kg

Cleaning method Drip cleaning system/reciprocating cleaning/dry and wet vacuum modes

Field of view 10×8mm

Reference point type Standard reference point/pad/opening

Visual system with up and down imaging/digital camera/geometric matching

positioning

System alignment accuracy and

repeatability

±12.5um@6σ, CPK≥2.0

Actual solder paste placement

repeatability

±18um@6σ, CPK≥2.0

Printing cycle <7.5sec

Power requirement AC220V±10%,50/60Hz,3KW

Compressed air requirement 4-6Kgf/cm²

Air consumption About 5L/min

Working environment temperature $-20^{\circ}\text{C} \sim +45^{\circ}\text{C}$

Working environment humidity 30%~60%

Dimensions (excluding three-color

light)

L1240×W1410×H1500 (mm)

www.smtbank.com

Room 207, Building 2, No. 5, Yangchong Industrial Zone, Songgang Street, Bao'an District, Shenzhen, Guangdong Province, China

Weight

About 1100Kg